Fig. 1

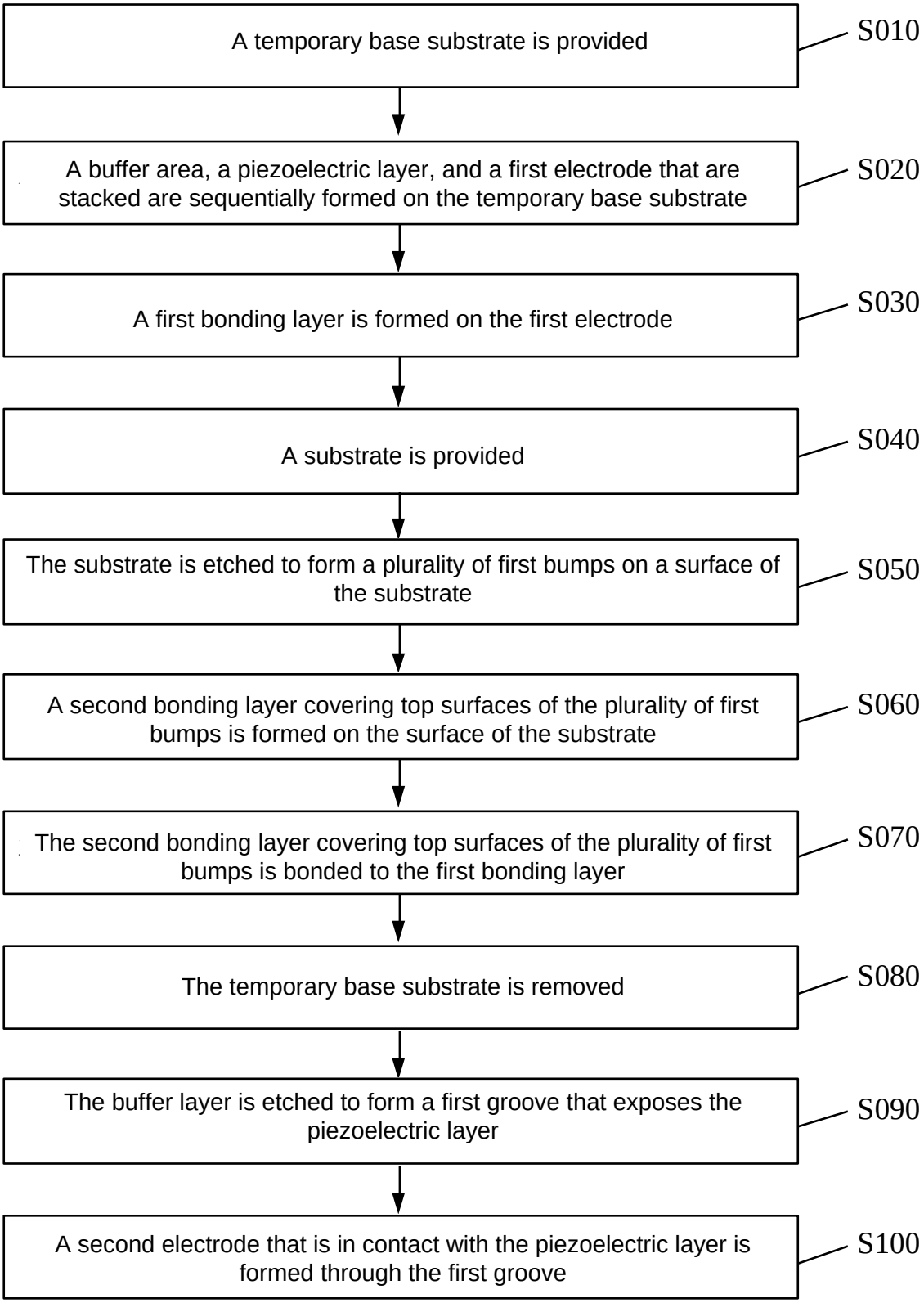

A temporary base substrate is provided
S010
A buffer area, a piezoelectric layer, and a first electrode that are stacked are sequentially formed on the temporary base substrate
S020
A first bonding layer is formed on the first electrode
S030
A substrate is provided
S040
The substrate is etched to form a plurality of first bumps on a surface of the substrate
S050
A second bonding layer covering top surfaces of the plurality of first bumps is formed on the surface of the substrate
S060
The second bonding layer covering top surfaces of the plurality of first bumps is bonded to the first bonding layer
S070
The temporary base substrate is removed
S080
The buffer layer is etched to form a first groove that exposes the piezoelectric layer
S090
A second electrode that is in contact with the piezoelectric layer is formed through the first groove
S100

Fig. 2

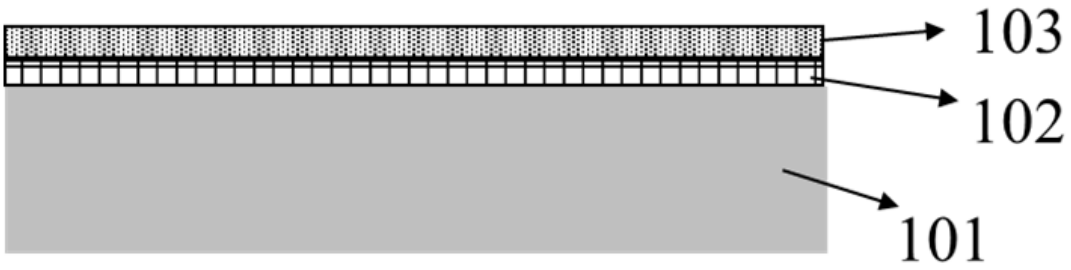


Fig. 3

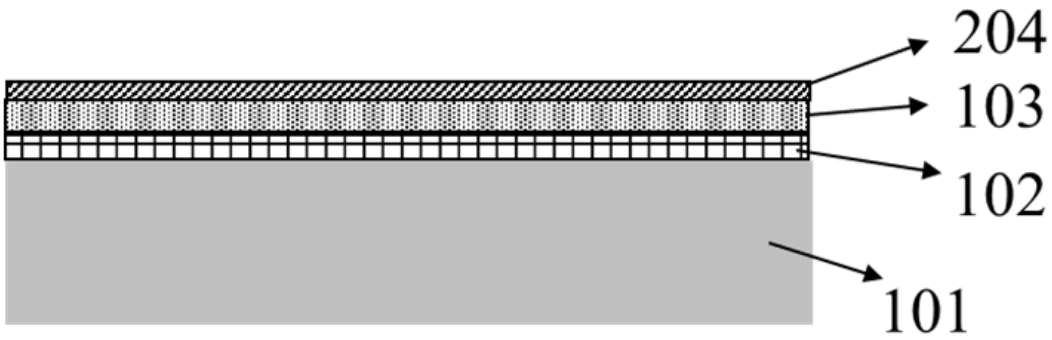


Fig. 4

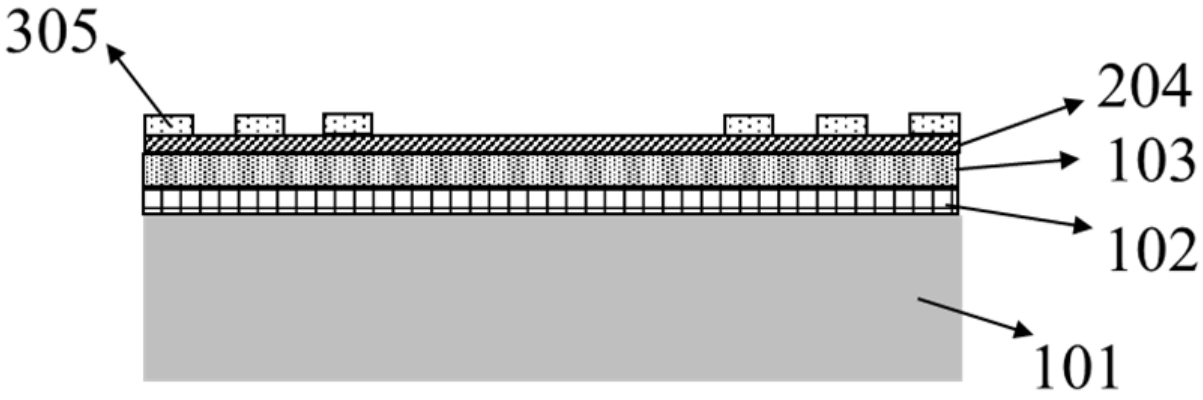


Fig. 5

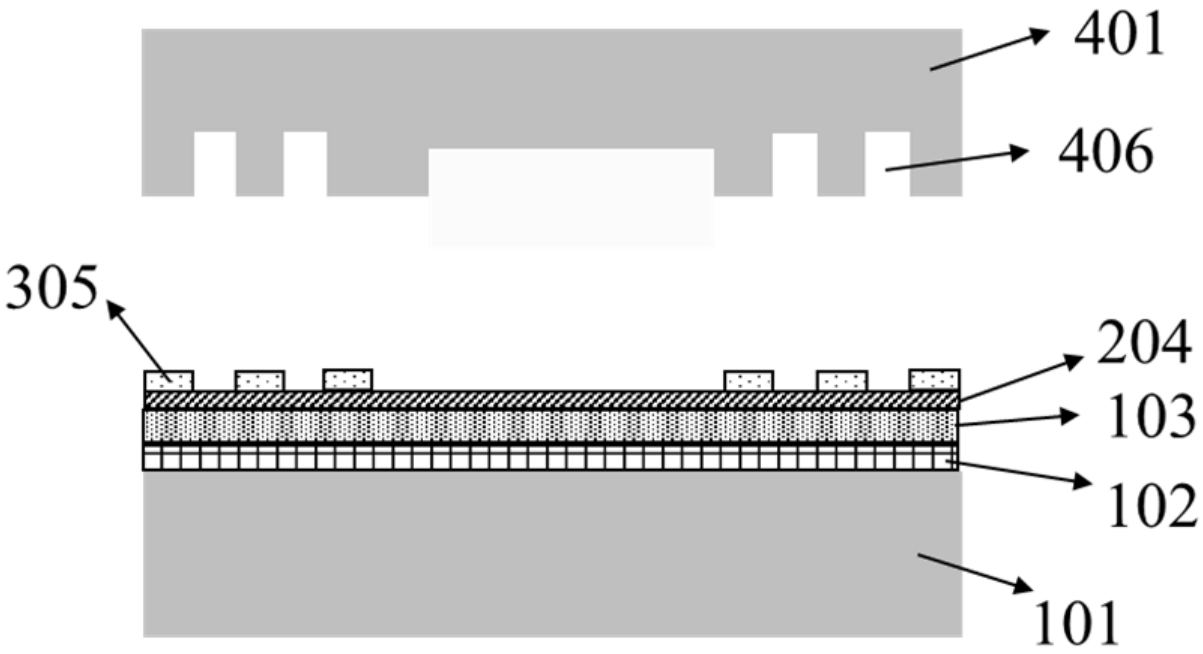


Fig. 6

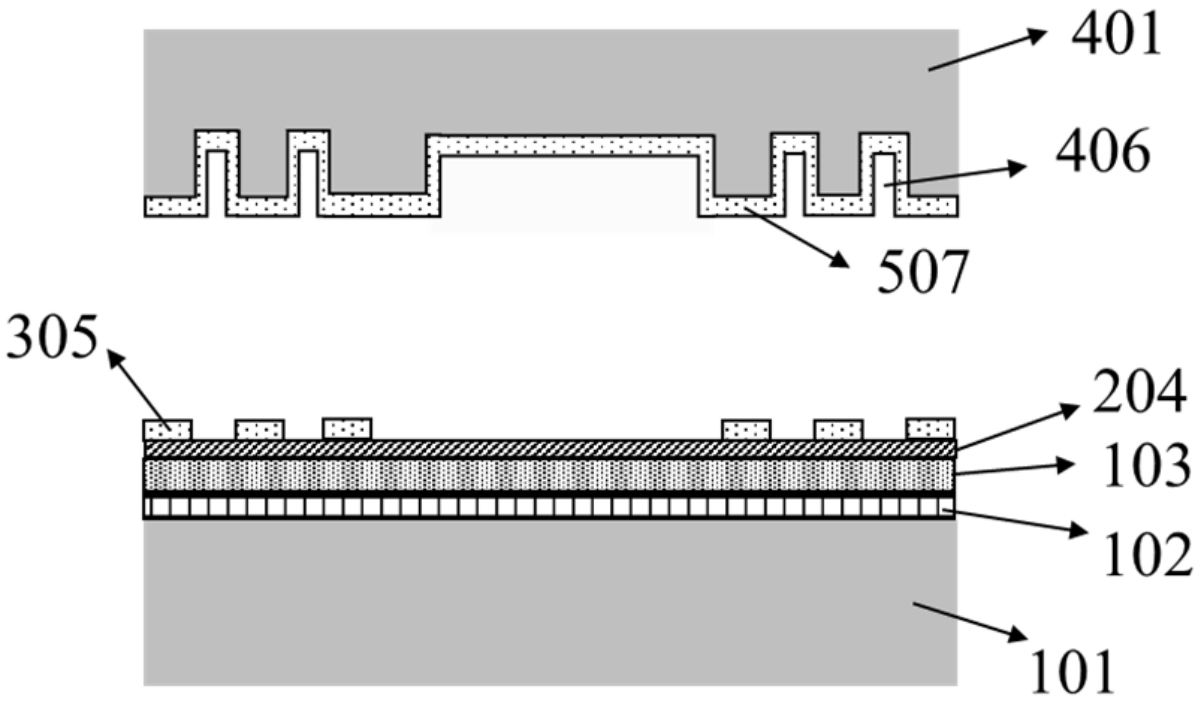


Fig. 7

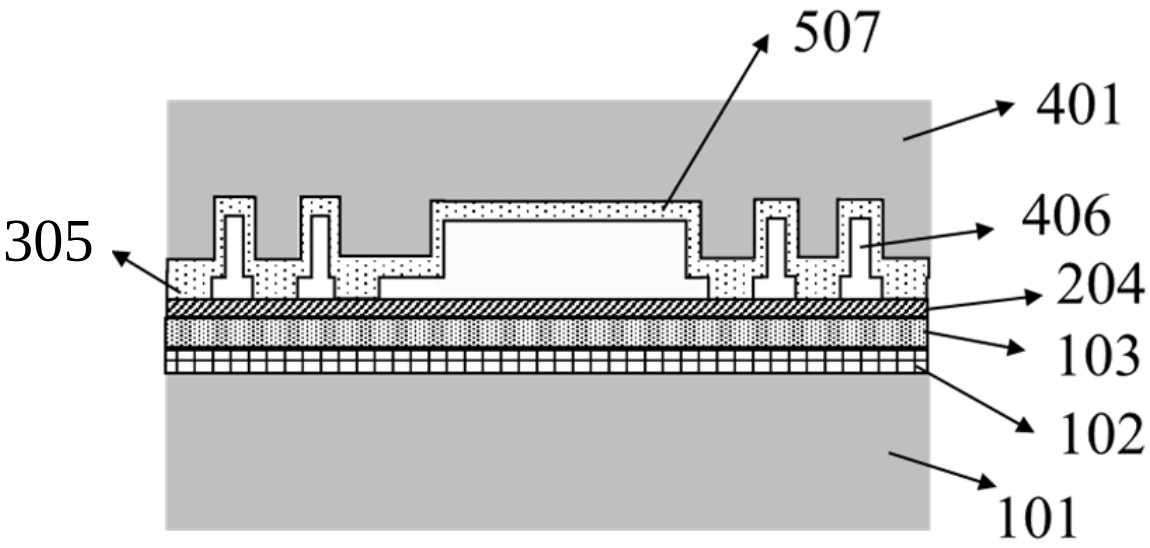


Fig. 8

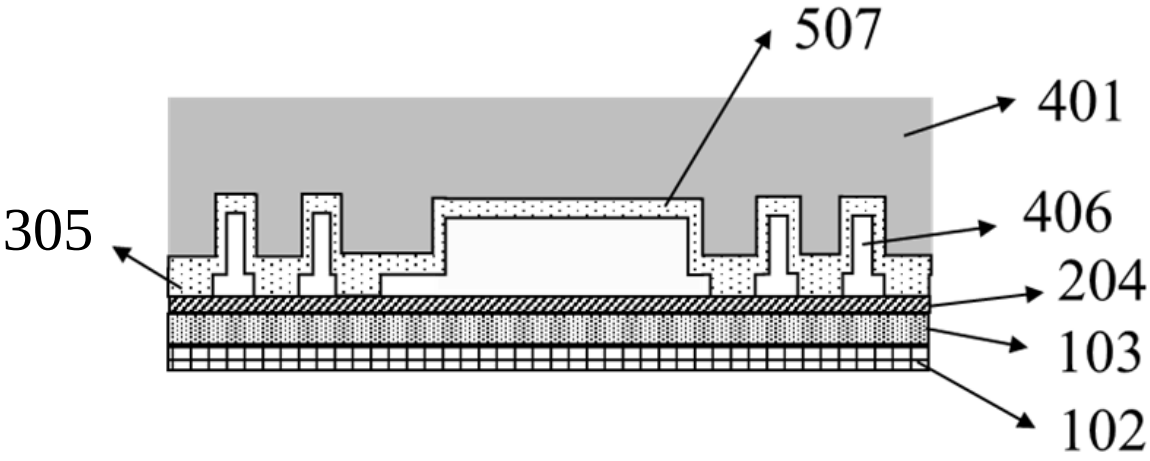


Fig. 9

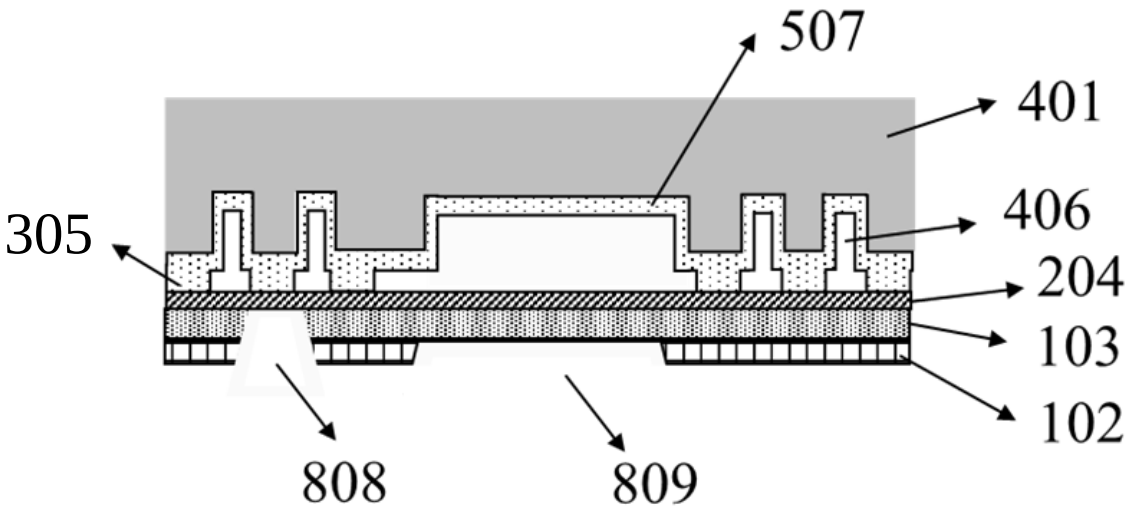

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Fig. 10

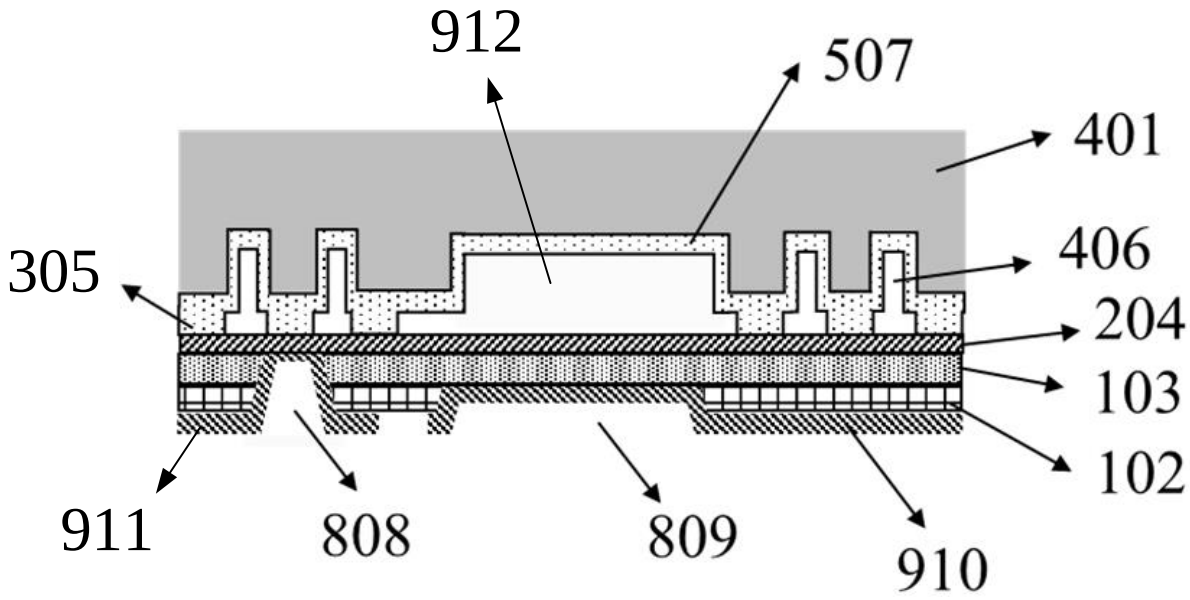

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Fig. 11

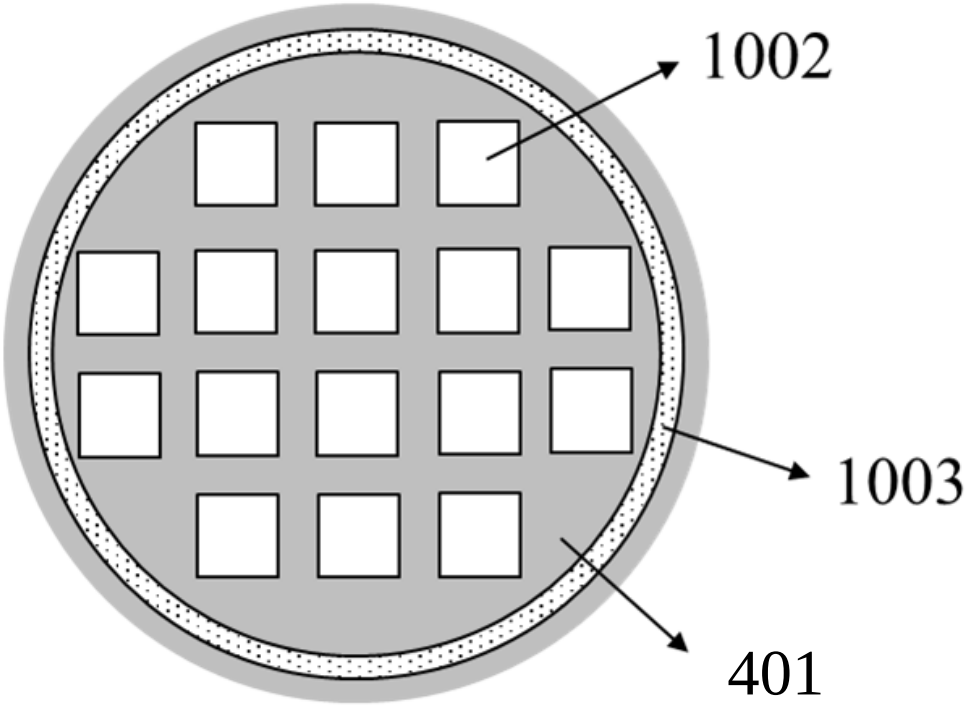


Fig. 12

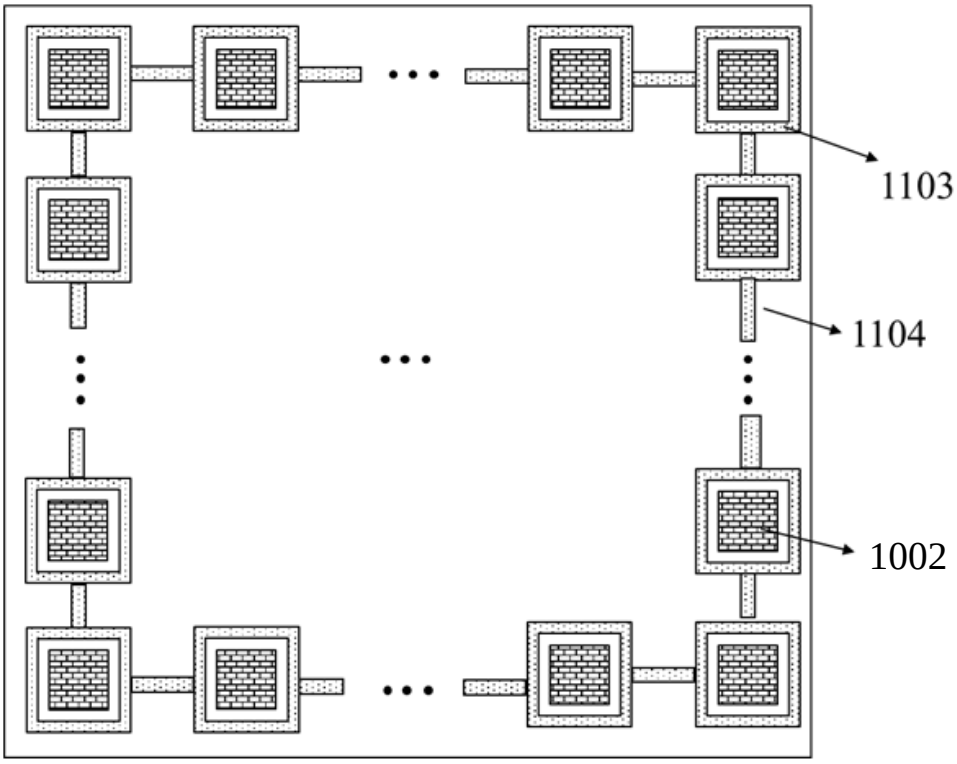


Fig. 13

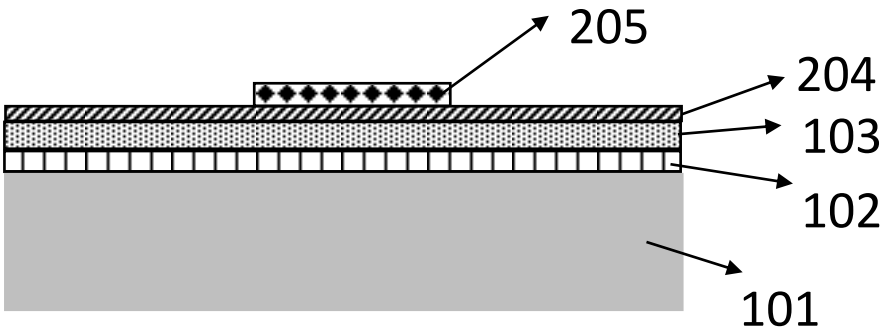


Fig. 14

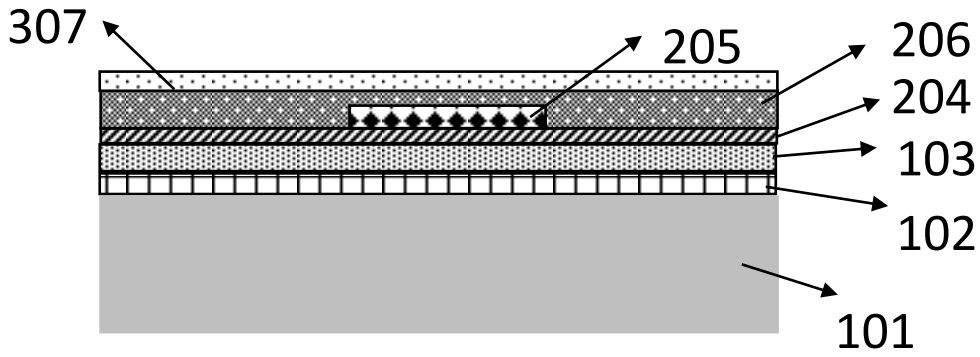


Fig. 15

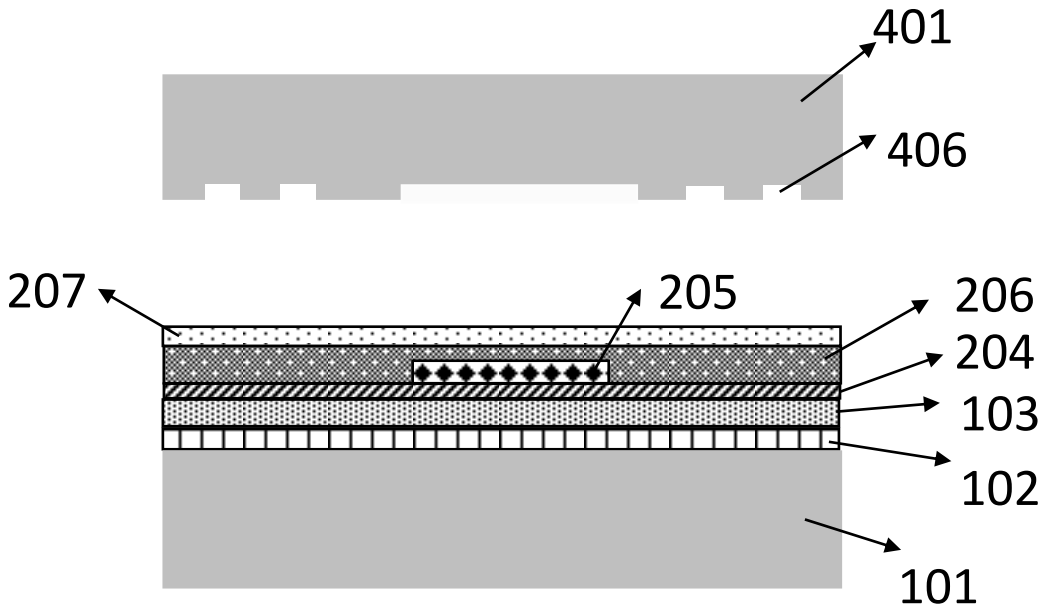


Fig. 16

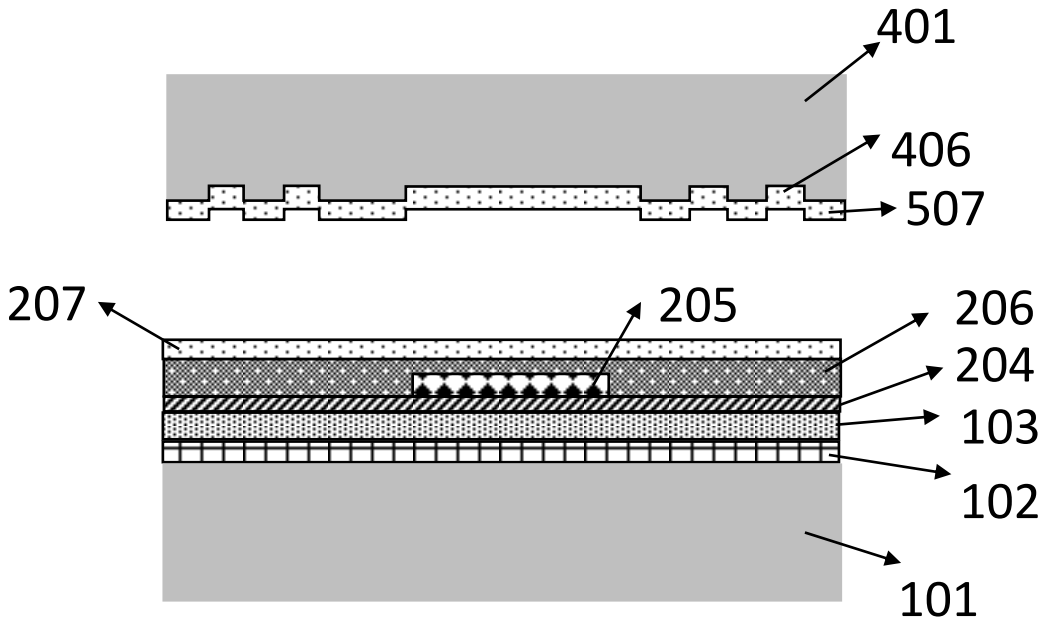

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Fig. 17

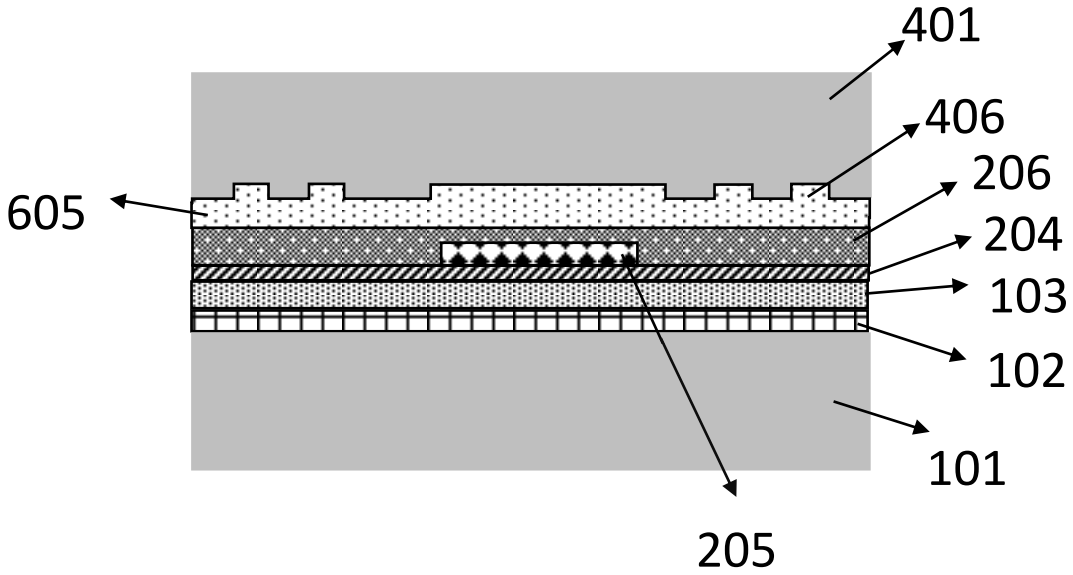

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Fig. 18

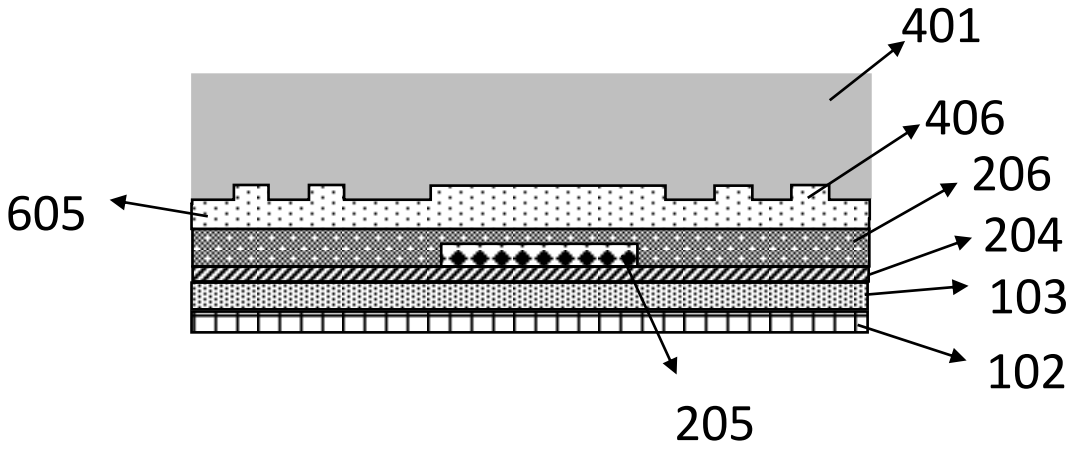

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Fig. 19

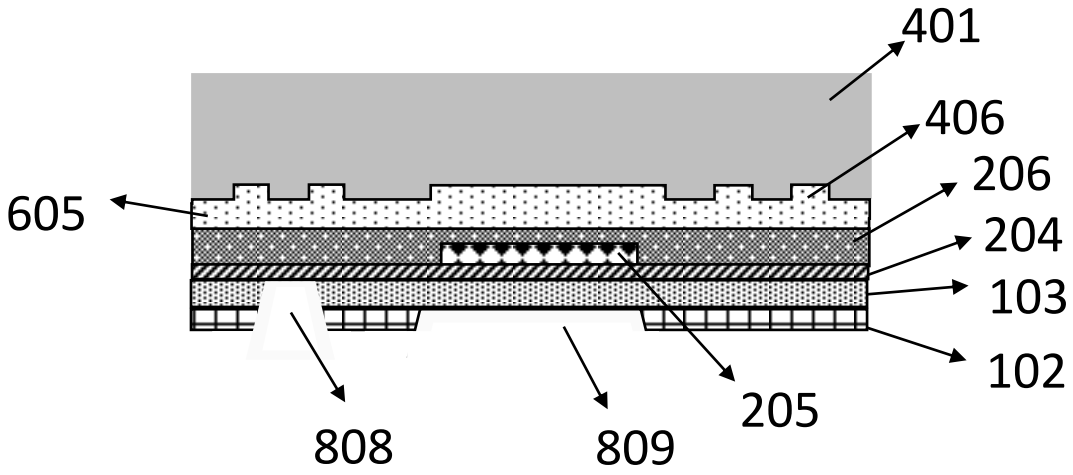

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Fig. 20

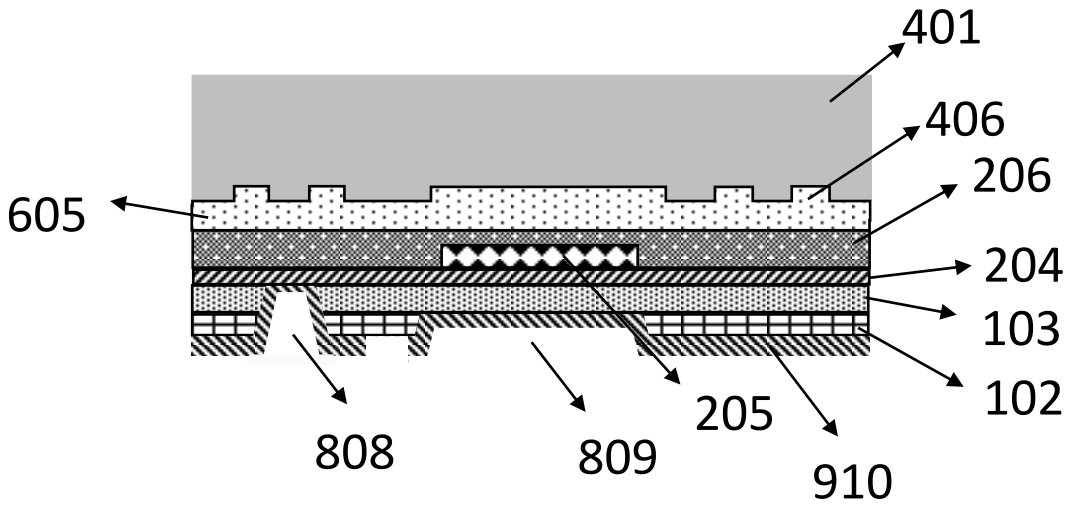

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Fig. 21

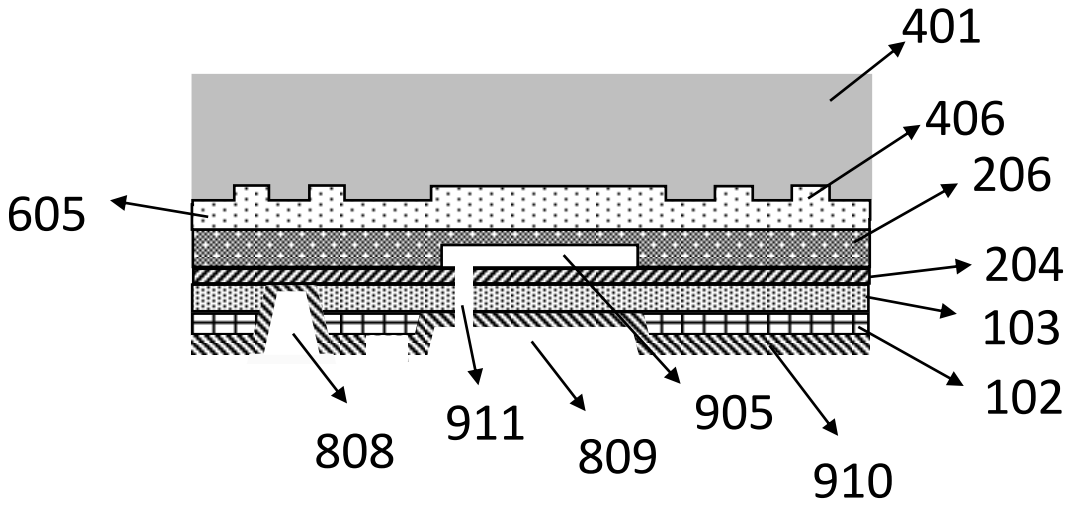

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Fig. 22

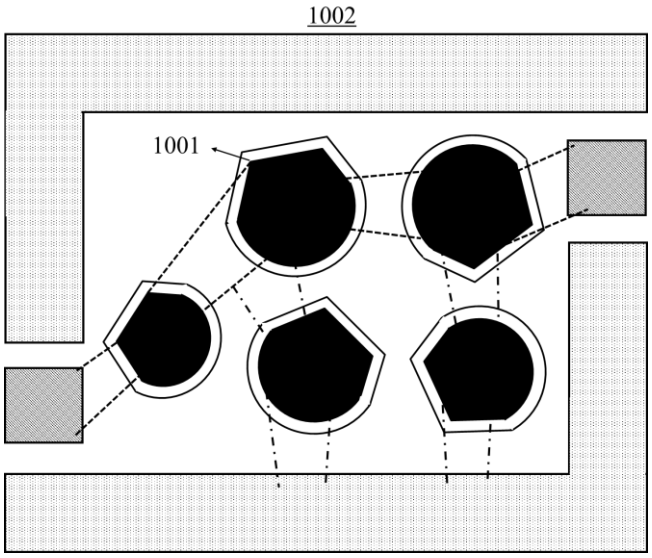


Fig. 23

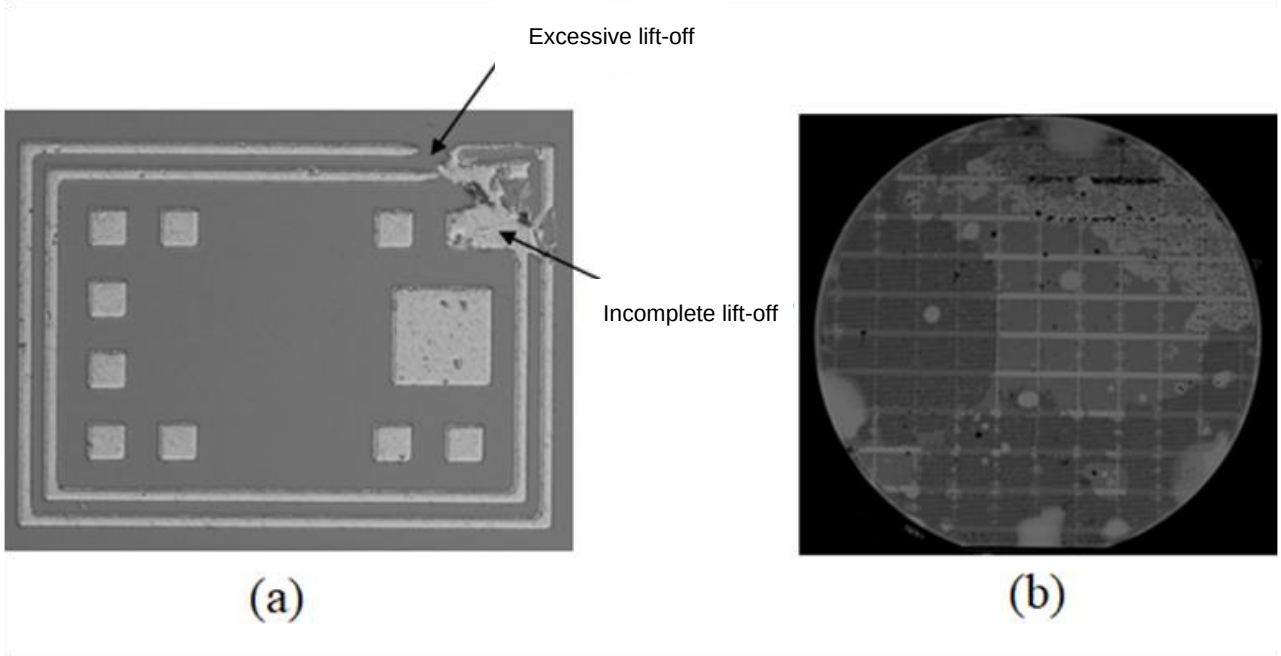


Fig. 24

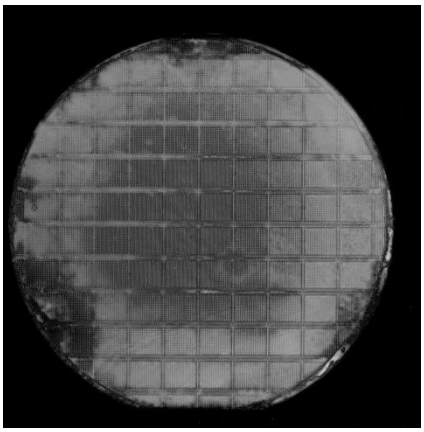


Fig. 25

